

Connector for SIM Card 8pins

SCGC Series



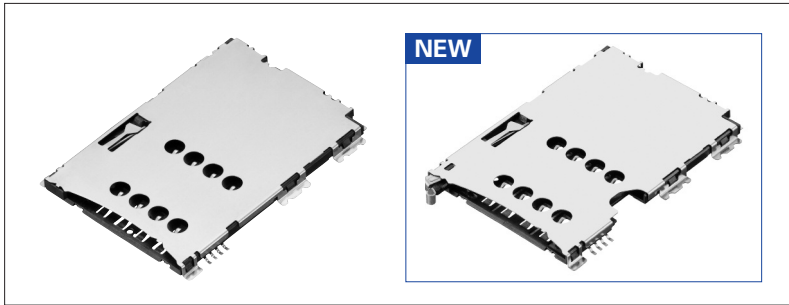
Small size surface mounting contributes to improved flexibility in set design.

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For Memory Stick Micro™



Combine Type

For W-SIM

Typical Specifications

Items		Specifications	
Structure	Applicable media	SIM Card 8pins	
	Mounting type	Surface mounting type	
	Mounting style	Standard mount	
	Media ejection structure	Push-push type	
Performance	Operating temperature range	-25°C to +60°C	
	Voltage proof	250V AC 1minute	
	Insulation resistance (Initial)	1,000MΩ min.	
	Contact resistance (Initial)	Connector contacts	100mΩ max.
		Detection switch	500mΩ max.
Insertion and removal cycle		5,000cycles	

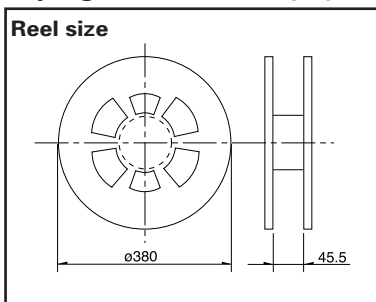
Product Line

Media ejection structure	Mounting style	Feature	Stand-off (mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	Without Card Lock	0	Taping	SCGC1B0101	1
		With Card Lock			SCGC1B0301	2

Packing Specifications

Taping

Unit:mm



Product No.	Number of packages (pcs.)			Tape width (mm)	Export package measurements (mm)
	1 reel	1 case /Japan	1 case /export packing		
SCGC1B0101	1,000	2,000	4,000	44	403 × 403 × 249
SCGC1B0301	1,400	2,800	5,600		

Note

Please place purchase orders per minimum order unit N (integer).



Automotive Use

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For Memory Stick Micro™

Combine Type


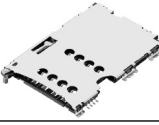

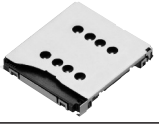
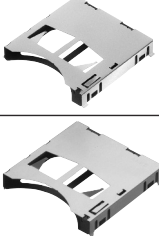
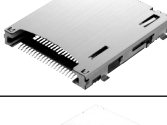
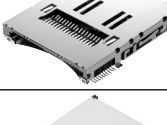

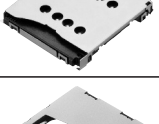



For W-SIM



Automotive Use

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
1		
2		

List of Varieties

Applicable media	Product No.	Photo	Media ejection structure	Mounting style	Features	Stand-off (mm)	Auto motive use	Page
SIM Card 8pins	SCGC1B0101			Standard mount	With switch		○	541
	SCGC1B0301				With Automatic Locking Cam			
Memory Stick Micro™	SCNA1A0300		Push-push type		Without boss			543
SD Memory Card Multi-Media Card™ Memory Stick™	SCDB3A0202				Reverse mount			
	SCDB4A0101							
SD Memory Card Multi-Media Card™ Multi-Media Card Plus™ Memory Stick™ xD-Picture Card™	SCDG1A0101			Standard mount				547
	SCDG2A0101							
SD Memory Card Multi-Media Card™ Memory Stick™ xD-Picture Card™	SCDG4B0100		Push-push type Manual insertion/removal		Thin with a Thickness of 4.2mm		—	549
microSD™ Card SIM Card 8pins	SCHG1B0100				microSD™ Card right insertion type			551
W-SIM	SCZA1A0100		Push-push type	Standard mount	Without boss L type			553
	SCZA1A0200				With boss L type			
	SCZA1A0300	Without boss 0.6mm type						
	SCZA1A0400	With boss 0.6mm type						
	SCZA1A0500	Without boss 1.2mm type						
	SCZA1A0600	With boss 1.2mm type						
	SCZA2A0100		Manual insertion/removal	With boss L type				
	SCZA2A0200			Without boss 0.6mm type				

For SD Memory Card
 For microSD™ Card
 For SIM Card 8pins
 For Memory Stick Micro™
 Combine Type
 For W-SIM

Note

○marks in "Available for automotive use" indicate that some of the series products can work at the operating temperature range from -40°C to +85°C.

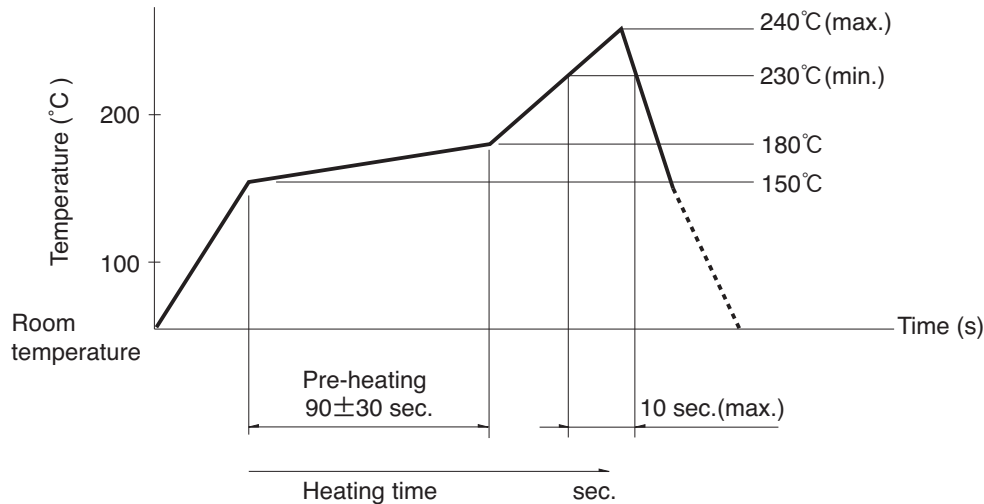
Note

Please place purchase orders per minimum order unit N (integer).

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T) at soldering portion.
3. Temperature profile



Please refer to each product's specification sheet to confirm temperature profile.

Cautions for using this product

1.Connector handling precautions

- (1) Safeguard the connector assembly against flux penetration from its top side.
- (2) This product is designed on the assumption that they will not be washed after soldering. If you wash it, it may cause deterioration of mechanically and electrically.

If washing is necessary, please make contact with us beforehand.

2. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions.

Caution is therefore required.

3. When soldering, do not use water soluble flux because this may corrode the product.

4. regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.

5. As P.W.B. warping may alter characteristics, please take this into consideration when designing pattern and layout.

6. Please do not solder at the ejector pushing position.

7. To prevent contact disturbance by the sulfuration or oxidation of the contact and terminal, and deterioration of solder ability by thin film on the terminal, please note following.

- Storage in the atmosphere of high temperature at 60 degrees or more, high humidity, corrosive gases such as sulfur or chlorine gas, and excessive piling up of the carton boxes shall be avoided.
- Connectors shall be stored as the package not opened and in the normal temperature and normal humidity, and the connectors shall be used preferably within 3 months, at least within 6 months.
- When the connectors are stored after opening the package, the connectors shall be sealed with a polyethylene bag etc. and stored in dark and cool place, avoiding direct sunlight. Bag etc. and stored in dark and cool place, avoiding direct sunlight. The connectors shall be used as soon as possible.

8. Don't push or hold down the metal cover of the connector, otherwise there is a possibility that the card would not be ejected or influences to other function.

9. Please attention following items to prevent connector from miss operation, such as bounding caused by ON/OFF switching and chattering by vibration.

- Repeated reading/writing.
- Establish delay time-recommended 400msec min.
- Establish CR accumulation circuit.

10. This product does not operate normally when the card which does not conform to the specification is used occasionally.

For
SD Memory
Card

For
microSD™
Card

For
SIM Card
8pins

For
Memory
Stick Micro™

Combine Type

For
W-SIM